

Next Generation Mezzanine
Connector development

“ TwinMezz™ ”

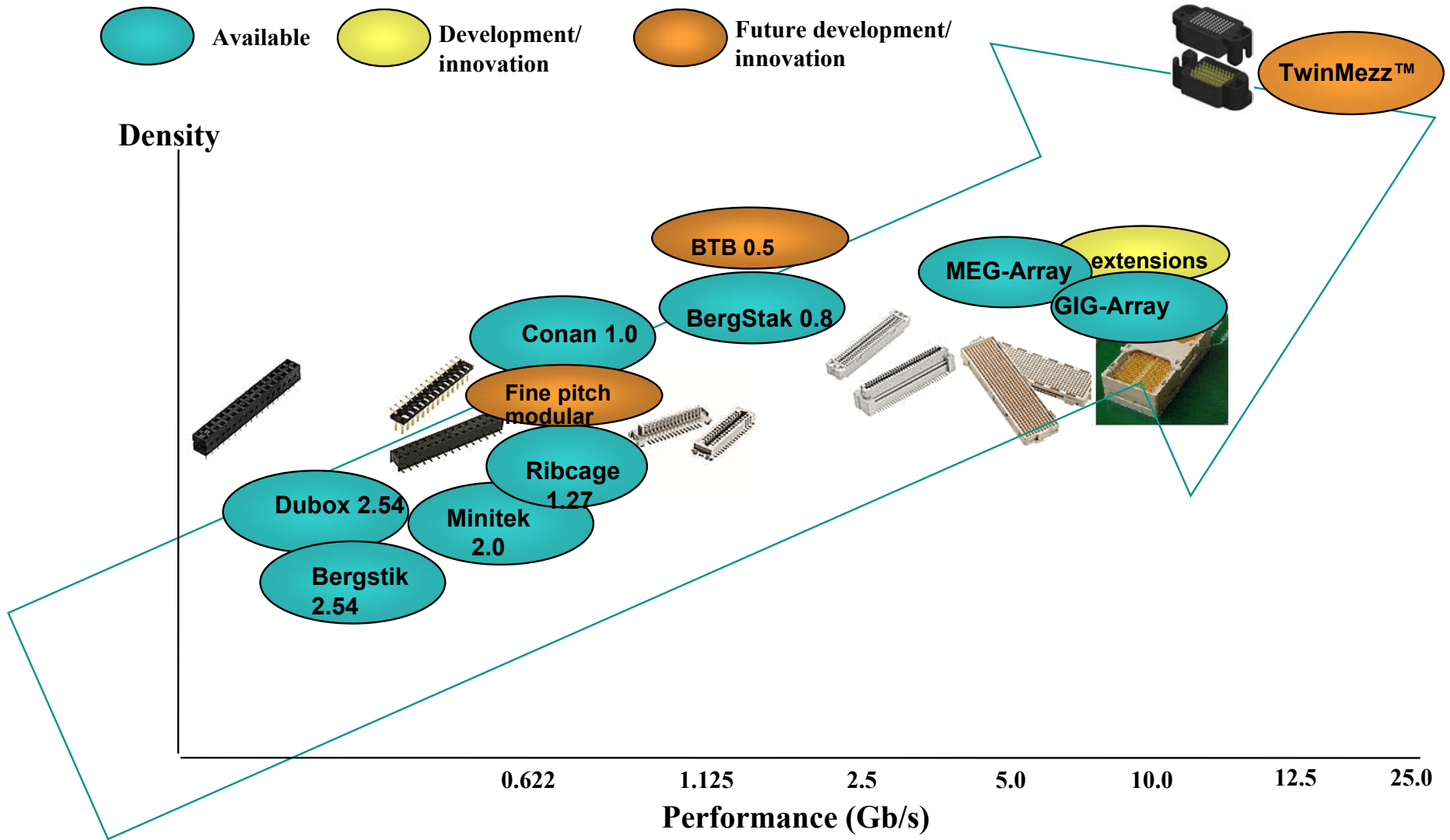
January , 2008



Mezzanine / Board-to-Board Roadmap

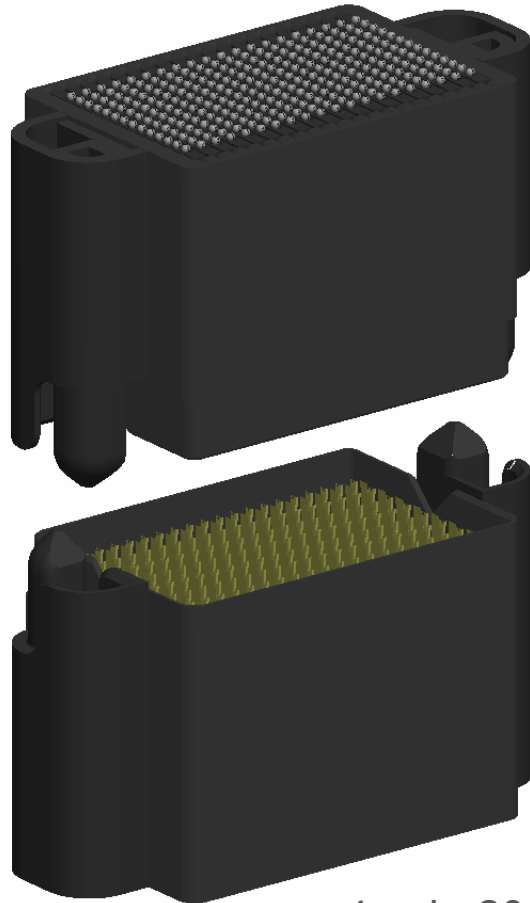


- Available
- Development/innovation
- Future development/innovation

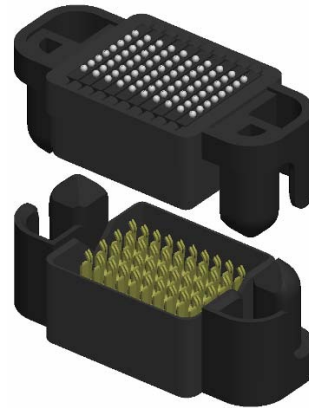


- Ultimately flexible:
 - Hermaphroditic design:
 - Expandable to multiple configurations (Both Height and Length)
 - Mated board to board stack height: range of 12 to 40 mm
 - Possible 2, 4 or 6 pair configurations
 - Open pin field: no internal bussing of grounds
- Reliable:
 - Dual beam contact design
 - Low Insertion Force, 15 grams/contact (Nominally)
 - 2.0mm nominal contact wipe
 - Integrated option for guidance
- Future proof:
 - Shield-less design for optimized cost and performance
 - Edge coupled differential pairs: 25Gbit/s signal speed
 - Bandwidth > 12.5 GHz (IL<1dB)
 - Low Cross-Talk
- Easy to process:
 - Pick and Place capability
 - Utilizes proven FCI Lead Free (RoHS compliant) SMT (BGA) technology
 - High density, 25 pairs per cm² (161 pairs per in²):
 - Contacts on a 1.0mm by 1.3mm pitch
 - 80 -800 contacts per assembly possible.

TwinMezz™ – Basic Views



4 pair, 20 column,
20mm high version shown
(40mm mated stack height)



2 pair, 10 column,
6mm high version shown
(12mm mated stack height)



2 pair, 40 column,
10mm high version shown
(20mm mated stack height)

- For availability of parts, planned production, design- and test data or any other product related documentation, please consult your local FCI sales representative or request information via: www.fciconnect.com/mezzselect or email us directly at: mezzselect@fciconnect.com